



Solid State Devices, Inc.

14830 Valley View Blvd * La Mirada, Ca 90638
 Phone: (562) 404-7855 * Fax: (562) 404-1773
 ssdi@ssdi-power.com * www.ssdi-power.com

SFF9140J

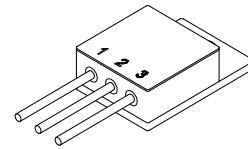
**-18 AMPS
 -100 VOLTS
 0.20 W
 P-CHANNEL
 POWER MOSFET**

Designer's Data Sheet

FEATURES:

- Rugged Construction with Poly Silicon Gate
- Low RDS(on) and High Transconductance
- Excellent High Temperature Stability
- Very Fast Switching Speed
- Fast Recovery and Superior dv/dt Performance
- Increased Reverse Energy Capability
- Low Input and Transfer Capacitance for Easy Paralleling
- Hermetically Sealed
- Replaces: IRF9140 Types
- TX, TXV, and Space Level Screening Available. Consult Factory.

TO-257



MAXIMUM RATINGS		Symbol	Value	Units
Drain to Source Voltage		V_{DS}	-100	Volts
Gate to Source Voltage		V_{GS}	± 20	Volts
Continuous Drain Current	$T_C = 25^\circ C$ $T_C = 100^\circ C$	I_D	-18 -11	Amps
Operating and Storage Temperature		$T_{OP} \text{ \& } T_{stg}$	-55 to +150	$^\circ C$
Thermal Resistance, Junction to Case		R_{qJC}	2.0	$^\circ C/W$
Total Device Dissipation	$T_C = 25^\circ C$ $T_C = 55^\circ C$	P_D	63 48	Watts
Single Pulse Avalanche Energy		E_{AS}	500	mJ
Repetitive Avalanche Energy		E_{AR}	12.5	mJ

PACKAGE OUTLINE:

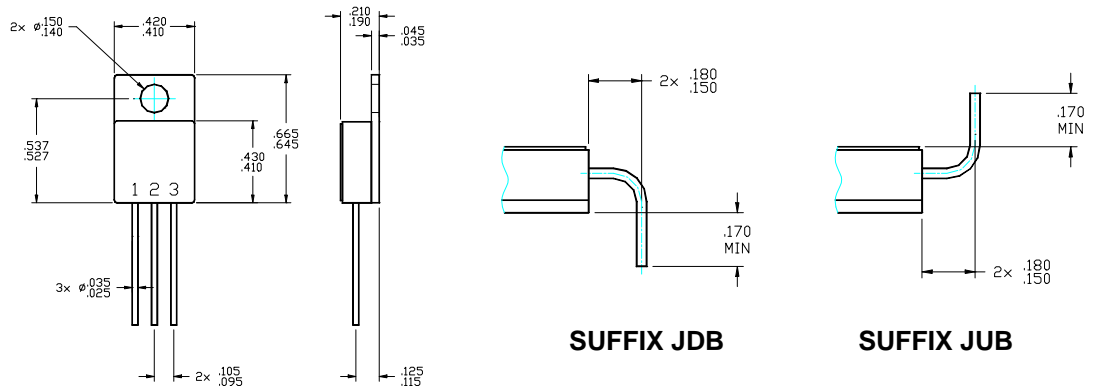
TO-257 (J)

PINOUT:

PIN 1: DRAIN

PIN 2: SOURCE

PIN 3: GATE



NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: FP0015G

DOC



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ELECTRICAL CHARACTERISTICS		Symbol	Min	Typ	Max	Unit
Drain to Source Breakdown Voltage ($V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$)		DBV_{DSS}	-100	—	—	Volts
Temperature Coefficient of Breakdown Voltage		$\frac{DBV_{DSS}}{T_J}$	—	0.087	—	Volts
Drain to Source ON State Resistance ($V_{GS} = -10\text{ V}$)	$I_D = 11\text{ A}$ $I_D = 18\text{ A}$	$R_{DS(on)}$	— —	0.15 —	0.20 0.23	W
Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$)		$V_{GS(th)}$	-2.0	—	-4.0	Volts
Forward Transconductance ($V_{DS} \geq 10\text{ V}$, $I_{DS} = 11\text{ A}$)		g_{fs}	6.1	8.0	—	S mho
Zero Gate Voltage Drain Current ($V_{DS} = 80\%$ rated V_{DS} , $V_{GS} = 0\text{ V}$) ($V_{DS} = 80\%$ rated V_{DS} , $V_{GS} = 0\text{ V}$, $T_A = 125^\circ\text{C}$)		I_{DSS}	— —	— —	25 250	mA
Gate to Source Leakage Forward Gate to Source Leakage Reverse	At rated V_{GS}	I_{gSS}	— —	— —	-100 100	nA
Total Gate Charge	$V_{GS} = -10\text{ Volts}$	Q_g	31	50	70	nC
Gate to Source Charge	50% rated V_{DS}	Q_{gs}	—	3	15	nC
Gate to Drain Charge	$I_D = -18\text{ A}$	Q_{gd}	7	25	45	nC
Turn ON Delay Time	$(V_{DD} = 50\%$ of rated V_{DS} rated I_D $R_G = 9.1\ \Omega$)	$t_{d(on)r}$	—	15	35	ns
Rise Time		t_r	—	8	85	
Turn OFF Delay Time		$t_{d(off)}$	—	35	85	
Fall Time		t_f	—	20	65	
Diode Forward Voltage ($I_S = \text{rated } I_D$, $V_{GS} = 0\text{ V}$, $T_J = 25^\circ\text{C}$)		V_{SD}	—	—	-4.2	Volts
Diode Reverse Recovery Time	$T_J = 25^\circ\text{C}$ $I_F = \text{rated } I_D$	t_{rr}	—	170	280	ns
Reverse Recovery Charge	$di/dt = 100\text{ A}/\mu\text{sec}$	Q_{RR}	—	—	3.6	mC
Input Capacitance	$V_{GS} = 0\text{ Volts}$	C_{iss}	—	1400	1650	ns
Output Capacitance	$V_{DS} = -25\text{ Volts}$	C_{oss}	—	600	740	
Reverse Transfer Capacitance	$f = 1\text{ MHz}$	C_{rss}	—	200	260	

